

LN2162C13TR

Surface Mounting Chip LED

GW Bi-Color Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

- Red

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	45	mW
Forward current	I_F	15	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	3	V
Operating ambient temperature	T_{opr}	-25 to +80	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +85	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color / Lens Color

- Red / Clear
- Green / Clear

- Green

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	45	mW
Forward current	I_F	15	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-25 to +80	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +85	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

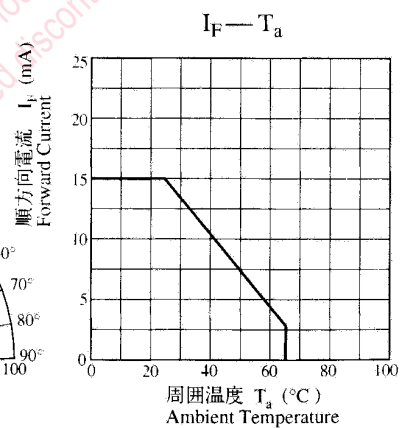
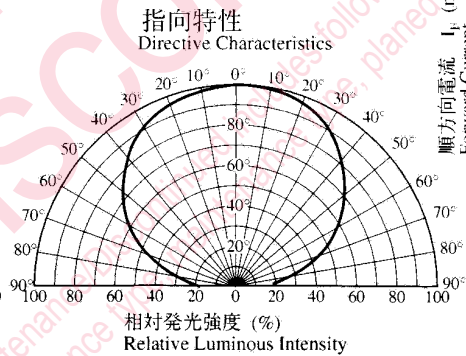
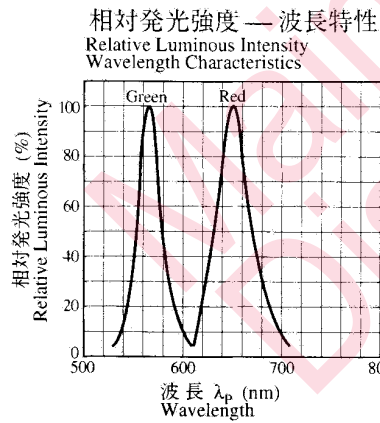
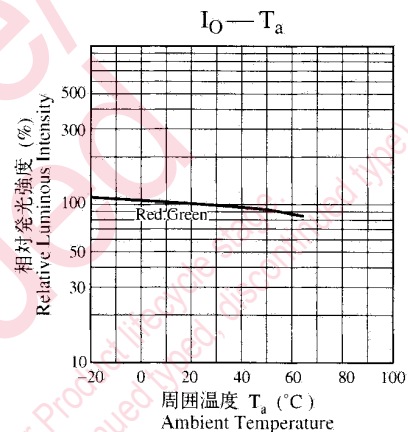
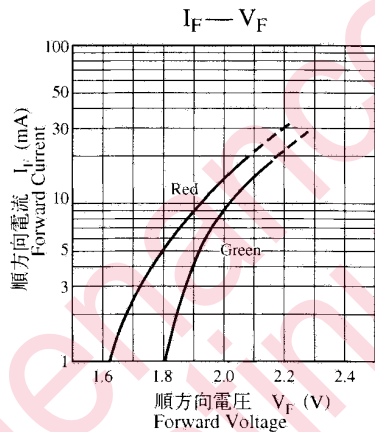
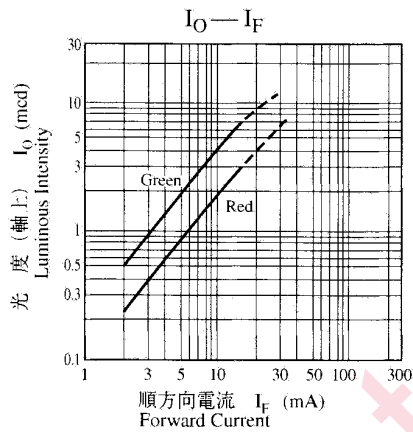
- Red

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		0.65	1.8		mcd
Forward current	I_F			10		mA
Forward voltage	V_F	$I_F = 10\text{ mA}$		2.0	2.8	V
Peak emission wavelength	λ_p	$I_F = 10\text{ mA}$		650		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		40		nm
Reverse current	I_R	$V_R = 3\text{ V}$			10	μA

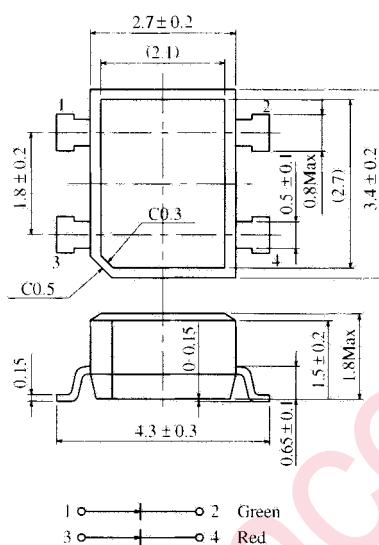
■ Electro-Optical Characteristics (Continued) $T_a = 25^{\circ}\text{C}$

• Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		1.5	4.0		mcd
Forward current	I_F			10		mA
Forward voltage	V_F	$I_F = 10\text{ mA}$		2.05	2.8	V
Peak emission wavelength	λ_P	$I_F = 10\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		30		nm
Reverse current	I_R	$V_R = 4\text{ V}$			10	μA



■ Package (Unit: mm)



• Pin name

- 1, 3: Anode
- 2, 4: Cathode

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